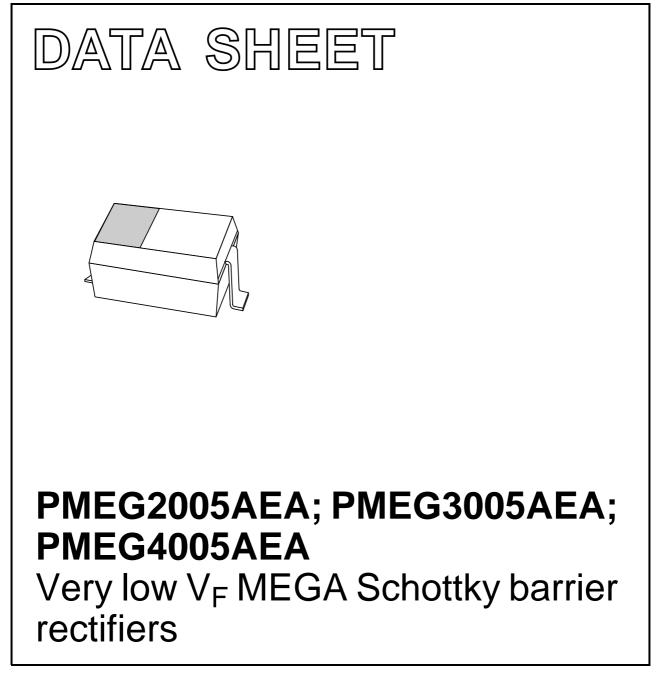
DISCRETE SEMICONDUCTORS



Product data sheet

2003 Aug 20



FEATURES

- Very low forward voltage
- High surge current
- Very small plastic SMD package.

APPLICATIONS

- Low voltage rectification
- High efficiency DC/DC conversion
- Voltage clamping
- Inverse polarity protection
- Low power consumption applications.

DESCRIPTION

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD323 (SC-76) very small SMD plastic package.

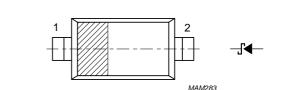
PMEG2005AEA; PMEG3005AEA; PMEG4005AEA

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
I _F	forward current	0.5	А
V _R	reverse voltage		
	PMEG2005AEA	20	V
	PMEG3005AEA	30	V
	PMEG4005AEA	40	V

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



The marking bar indicates the cathode.

Fig.1 Simplified outline (SOD323; SC-76) and symbol.

MARKING

TYPE NUMBER	MARKING CODE
PMEG2005AEA	E5
PMEG3005AEA	E4
PMEG4005AEA	E3

RELATED PRODUCTS

TYPE NUMBER	DESCRIPTION	FEATURE
PMEGxx05AEV	0.5 A; 20/30/40 V very low V_F MEGA Schottky rectifier	SOT666 package
PMEG2005EB	0.5 A; 20 V very low V _F MEGA Schottky rectifier	smaller SOD523 (SC-79) package
PMEG2010EA	1 A; 20 V very low V _F MEGA Schottky rectifier	higher forward current

PMEG2005AEA; PMEG3005AEA; PMEG4005AEA

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _R	continuous reverse voltage				
	PMEG2005AEA		_	20	V
	PMEG3005AEA		_	30	V
	PMEG4005AEA		_	40	V
I _F	continuous forward current	note 1	-	0.5	А
I _{FRM}	repetitive peak forward current	$t_p \le 1 \text{ ms}; \delta \le 0.5$	_	3.5	А
I _{FSM}	non-repetitive peak forward current	t _p = 8 ms; square wave	_	10	А
Tj	junction temperature	note 2	_	150	°C
T _{amb}	operating ambient temperature	note 2	-65	+150	°C
T _{stg}	storage temperature		-65	+150	°C

Notes

- 1. Refer to SOD323 (SC-76) standard mounting conditions.
- 2. For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses. Nomograms for determination of the reverse power losses P_R and $I_{F(AV)}$ rating will be available on request.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to	in free air; notes 1 and 2	450	K/W
	ambient	in free air; notes 2 and 3	210	K/W
R _{th j-s}	thermal resistance from junction to soldering point	note 4	90	K/W

Notes

- 1. Refer to SOD323 (SC-76) standard mounting conditions.
- 2. For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses. Nomograms for determination of the reverse power losses P_R and $I_{F(AV)}$ rating will be available on request.
- 3. Device mounted on an FR4 printed-circuit board with copper clad 10×10 mm.
- 4. Solder point of cathode tab.

PMEG2005AEA; PMEG3005AEA; PMEG4005AEA

ELECTRICAL CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

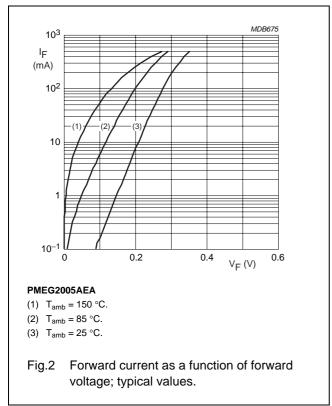
SYMBOL	DADAMETED	CONDITIONS	PMEG2005AEA		PMEG3005AEA		PMEG4005AEA		
	PARAMETER		TYP.	MAX.	TYP.	MAX.	TYP.	MAX.	UNIT
V _F	forward voltage	I _F = 0.1 mA	90	130	90	130	95	130	mV
		I _F = 1 mA	150	190	150	200	155	210	mV
		I _F = 10 mA	210	240	215	250	220	270	mV
		I _F = 100 mA	280	330	285	340	295	350	mV
		I _F = 500 mA	355	390	380	430	420	470	mV
I _R	continuous reverse	V _R = 10 V; note 1	15	40	12	30	7	20	μΑ
	current	V _R = 20 V; note 1	40	200	-	-	_	-	μA
		V _R = 30 V; note 1	_	_	40	150	_	_	μΑ
		V _R = 40 V; note 1	-	_	-	-	30	100	μA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz	66	80	55	70	43	50	pF

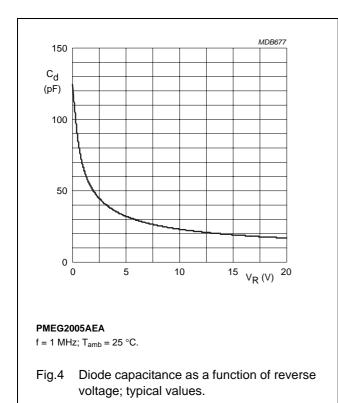
Note

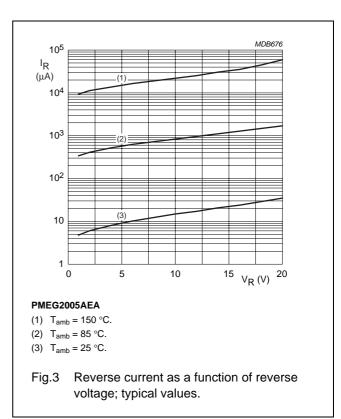
1. Pulse test: $t_p \leq 300~\mu\text{s};~\delta \leq 0.02.$

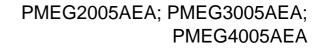
PMEG2005AEA; PMEG3005AEA; PMEG4005AEA

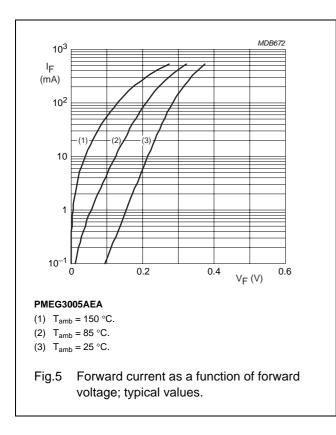
GRAPHICAL DATA

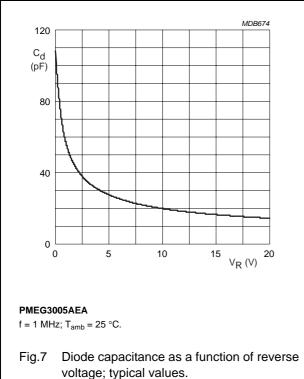


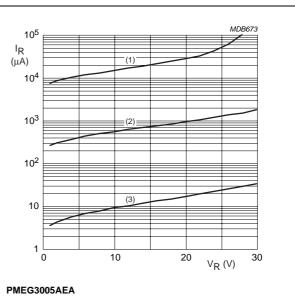








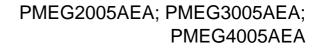


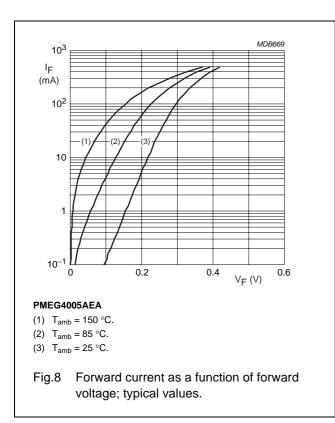


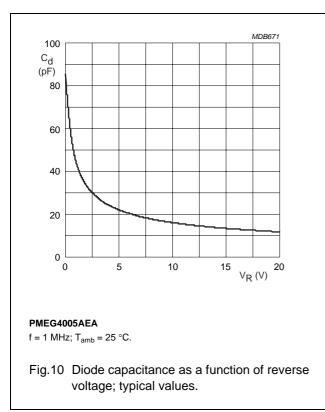
(1) $T_{amb} = 150 \ ^{\circ}C.$

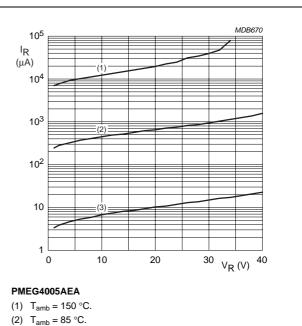
(2) $T_{amb} = 85 \ ^{\circ}C.$

- (3) $T_{amb} = 25 \ ^{\circ}C.$
- Fig.6 Reverse current as a function of reverse voltage; typical values.









(3) $T_{amb} = 25 \ ^{\circ}C.$

Fig.9 Reverse current as a function of reverse voltage; typical values.

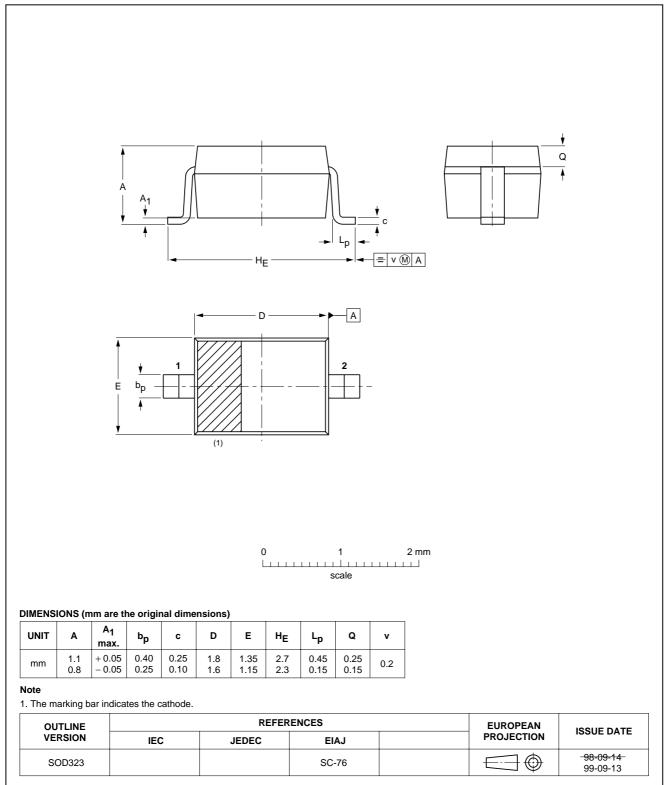
PMEG4005AEA

PMEG2005AEA; PMEG3005AEA;

Very low V_F MEGA Schottky barrier rectifiers

PACKAGE OUTLINE

Plastic surface mounted package; 2 leads



SOD323

PMEG2005AEA; PMEG3005AEA; PMEG4005AEA

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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